

IN THE CLAIMS:

dl (1) Please amend Claim 1 as follows:

1. (Three times amended) An integrated circuit comprising:
a substrate having interconnects for interconnecting integrated circuit devices;
a plurality of bond pads formed above the substrate; and
a first conductive trace formed at an outer region of the substrate and coupled to at least two of the plurality of bond pads, the first conductive trace and at least two bond pads electrically isolated from the interconnects.

(2) Please amend Claim 10 as follows:

d2 10. (Three times amended) An integrated circuit comprising:
a substrate having interconnects for interconnecting integrated circuit devices;
a plurality of bond pads; and
a conductive tester runner formed on the substrate and around the plurality of bond pads and electrically coupled to at least two of the plurality of bond pads, the conductive tester runner and at least two bond pads electrically isolated from the interconnects.
